

**VERSION WITH MARKINGS TO SHOW CHANGES MADE (CLAIMS)**

1. (Amended) A flexible printed circuit board comprising a component mount section, which an electronic component is mounted on, and a cable section, which connects to the component mount section;  
circuit patterns being provided ~~on~~ in the cable section, and covered by a soft laminated adhesive, the adhesive being an outermost layer of the cable section.
3. (Amended) The flexible printed circuit board as described in Claim 1, the laminated adhesive comprising a ~~polyamide~~ polyimide adhesive.
5. (Amended) A method for manufacturing a flexible printed circuit board having a component mount section, which comprises an outer-layer material laminated on an inner-layer material with an insulating cover therebetween, and a cable section, which comprises the inner-layer material covered by the insulating cover and connects to the component mount section, the method comprising the step of:  
covering the inner-layer material of the component mount section and the cable section with a soft laminated adhesive, the soft laminated adhesive being an outermost layer of the cable section.

**VERSION WITH MARKINGS TO SHOW CHANGES MADE (SPECIFICATION)**

On page 3, please replace the paragraph spanning lines 9-16 with the following:

Since the laminating adhesive 3 is the outermost layer of the cable section, it is preferable that the material used for the laminating adhesive 3 should be properly hard and soft enough to function as a cable section while capable of maintaining an average thickness. Materials, which satisfy these conditions, include ~~polyamide~~ polyimide and acrylic adhesives. A thin film of such material can be provided evenly over the surface of the inner-layer material 1.